

IN THE CLAIMS:

All of the claims that remain pending and under consideration in the above-referenced application are presented, pursuant to 37 C.F.R. §§1.121(c)(1)(i) and 1.121(c)(3), in clean form below. Claim 52 has been amended. Please enter these claims as amended. Also attached is a marked-up version of the claims, as amended herein, pursuant to 37 C.F.R. § 1.121(c)(1)(ii).

Please amend the claims as follows:

52. (Amended) A socket contact formation process, comprising:

forming a contact head from a conductive material;

forming a contact body from a semiconductive material configured to be electrically conductive; and

joining said contact head and said contact body.

53. The process in claim 52, wherein:

said step of forming a contact head comprises stamping a metal element;

said step of forming a contact body comprises etching silicon; and

said step of joining said contact head and said contact body further comprises adhering said contact head onto said contact body.

54. The process in claim 52, wherein said step of joining said contact head and said contact body further comprises depositing a metal over a silicon surface.